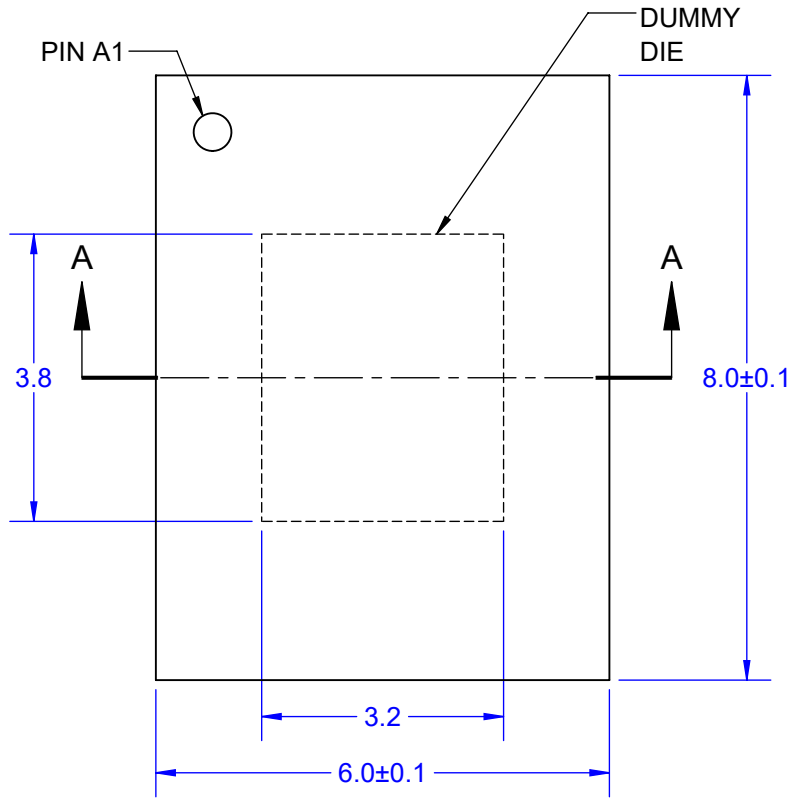
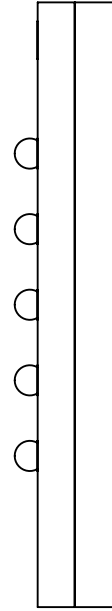


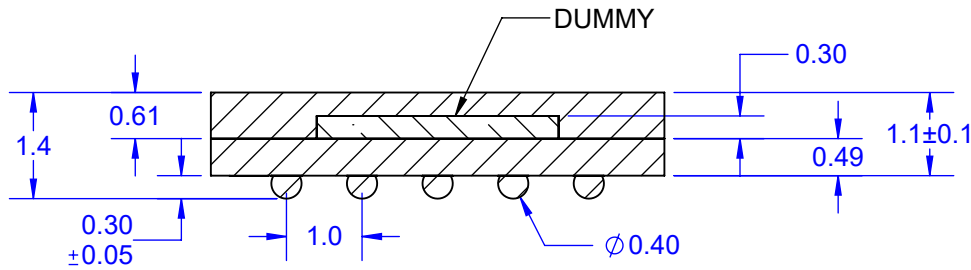
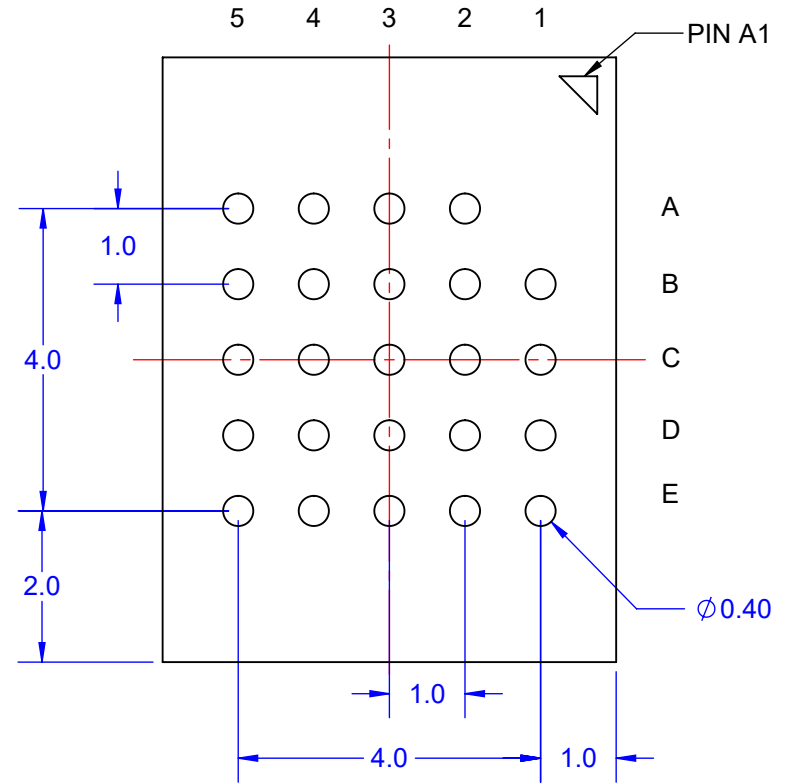
HCD'J'9K



G89'J'9K



65 @@J'9K



SECTION A-A
SCALE 10 : 1

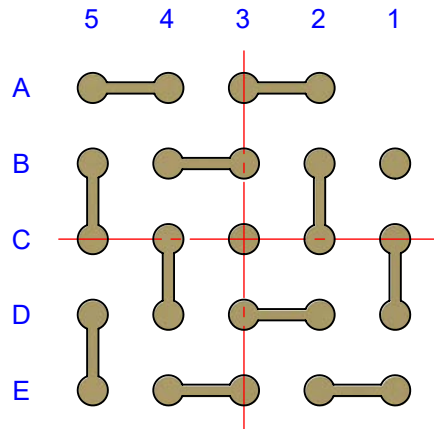
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.40mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.35mm.
- 5) PAD Cu DIAMETER: 0.40mm.
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE SIZE IS OPTIONAL.
- 8) MSL-3 RECOMMENDED BAKING 24 HOURS @125°C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

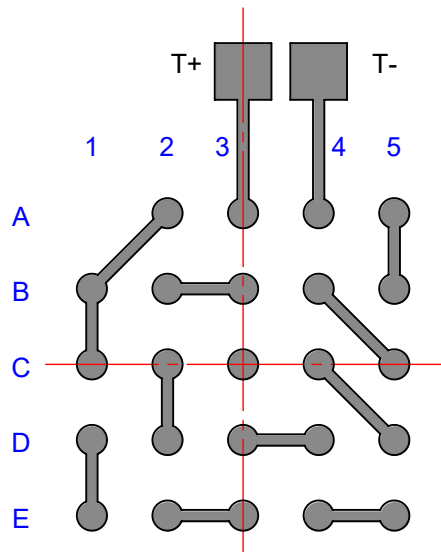
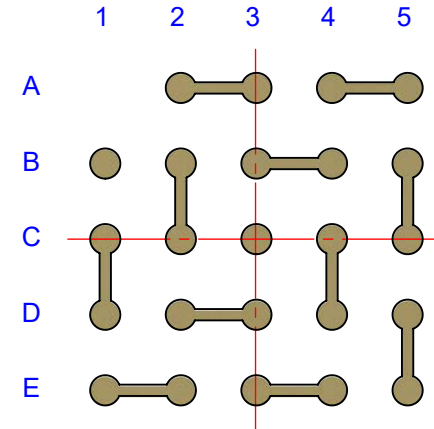
D5FH'BI A69F'H56 @				
D5FH'BI A69F	65 @@5 @CM	DVI: fYY	Fc<G	GJ'89
BGA24T1.0C-DC057D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA24T1.0-DC057D	Sn63/Pb37	NO	NO	YES

APPROVALS	DATE				
DRAWN T.Au	10/7/2025				
ENG M. Hart	10/7/2025	TITLE BGA24T1.0C-DC057D DAISY CHAIN			
MFG		SCALE 10:1	SIZE A	DRAWING NO. 510573	REV A
QA		DO NOT SCALE DRAWING		SHEET 1 OF 3	
CUST					
REVISED					

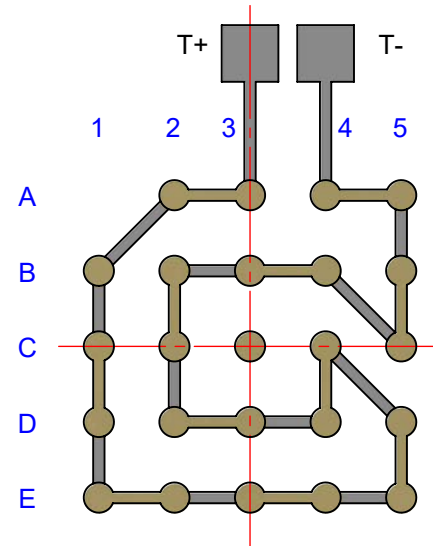
65 @@J9K



6 CHHCA 'G-89 'fHCD'L!F5 MJ9K L



H9GH'J9<7 @'6 C5 F8



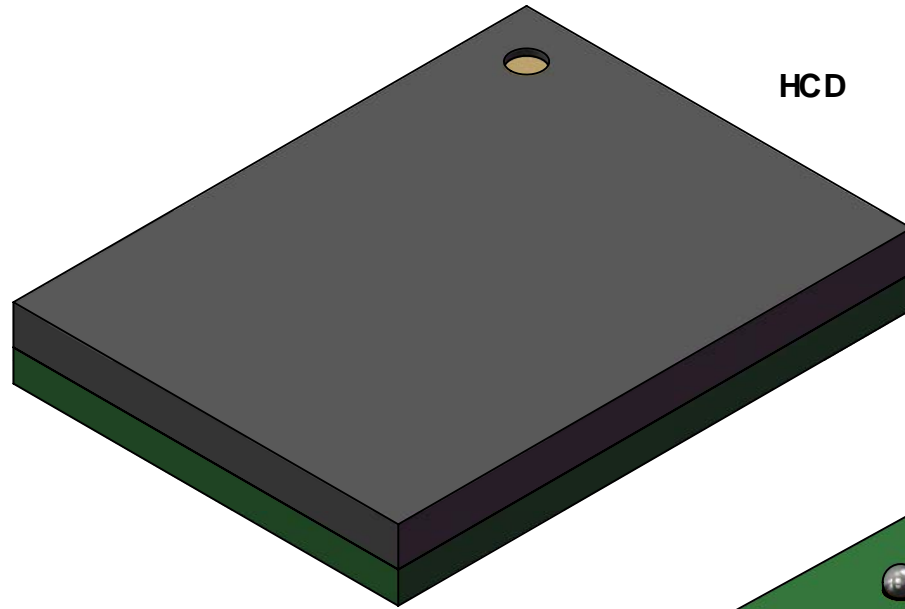
5 : H9F'ACI BH-B;

Notes:

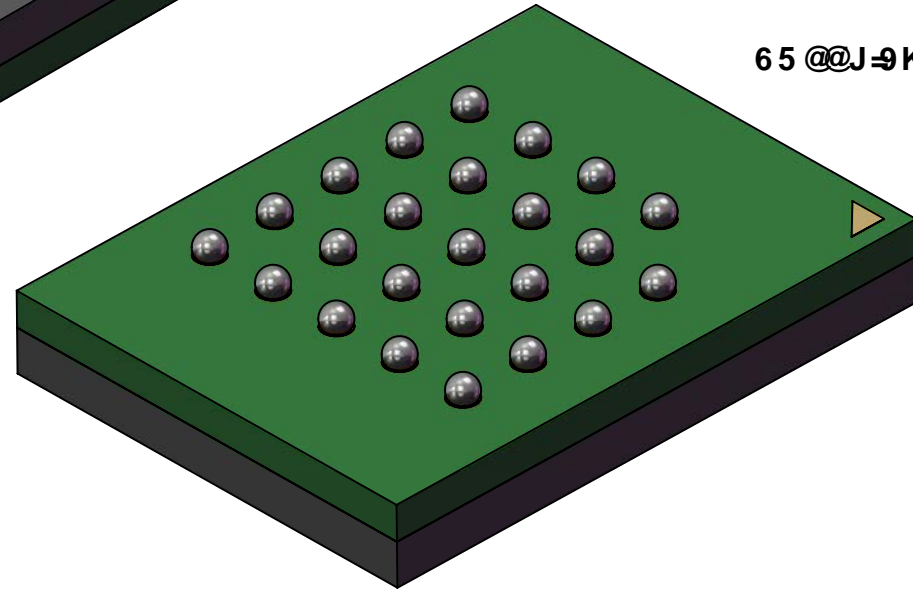
- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL DIAMETER 0.40mm (16 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.150mm (6 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.35mm (13.8 MIL).

TopLine[®]			
TITLE		BGA24T1.0C-DC057D DAISY CHAIN	
SCALE	SIZE	DRAWING NO.	REV
10:1	A	510573	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

AC89@



HCD



65 @@J-K

TopLine[®]

TITLE BGA24T1.0C -DC057D
DAISY CHAIN

SCALE 12:1	SIZE A	DRAWING NO. 510573	REV A
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DO NOT SCALE DRAWING SHEET 3 OF 3